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1 Transient analysis of single interconnects characterized with measured S-parameter data

Wang, J.S.-H.; Dai, W.W.-M.;

Electrical Performance of Electronic Packaging, 1996., IEEE 5th Topical

Meeting, 28-30 Oct. 1996

Pages:159 - 161

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2 Simple modeling of coplanar waveguide on thick dielectric over lossy substrate

Jin-Su Ko; Bon-Kee Kim; Kwyro Lee;

Electron Devices, IEEE Transactions on, Volume: 44, Issue: 5, May 1997

Pages:856 - 861

[\[Abstract\]](#) [\[PDF Full-Text \(172 KB\)\]](#) **IEEE JNL**

3 Simulating RF circuits using PSpice

Goss, P.;

Effective Microwave CAD (Ref. No: 1997/377), IEE Colloquium on, 3 Dec. 1997

Pages:10/1 - 10/5

[\[Abstract\]](#) [\[PDF Full-Text \(208 KB\)\]](#) **IEE CNF**

4 Accurate power supply and ground plane pair models [for MCMs]

Wu, H.H.; Meyer, J.W.; Keunmyung Lee; Barber, A.;

Advanced Packaging, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on], Volume: 22, Issue: 3, Aug. 1999

Pages:259 - 266

[\[Abstract\]](#) [\[PDF Full-Text \(268 KB\)\]](#) **IEEE JNL**

5 Extraction of accurate package models from VNA measurements

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